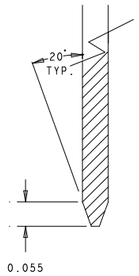
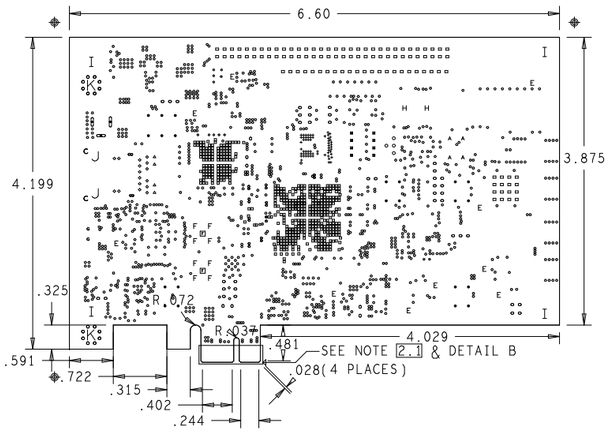
REVISIONS			
REV	DESCRIPTION	DATE	APPROVAL
A	INTIAL RELEASE	JUN-2013	
B	COMPONENT CHANGES	AUG-2013	
C	FEW COMPONENTS REMOVED	SEP-2013	
D	EDGE SMA AND SILK UPDATED	JAN-2014	
E	PROGRAMMING CIRCUIT UPDATED	OCT-2015	



DETAIL B (EDGE BEVEL)

SCALE = NONE



PACTRON
DATE: OCT 2015
PROJECT NAME: M2GL-M2S-EVAL-KIT REV: E
FILM LAYER: FAB

DRILL CHART: TOP to BOTTOM				
ALL UNITS ARE IN MILS				
FIGURE	SIZE	TOLERANCE	PLATED	QTY
·	8.0	+3.0/-8.0	PLATED	62
▫	10.0	+3.0/-3.0	PLATED	506
•	10.0	+3.0/-3.0	PLATED	1198
·	25.0	+3.0/-3.0	PLATED	12
▪	31.0	+3.0/-3.0	PLATED	8
○	35.0	+3.0/-3.0	PLATED	16
◦	35.0	+5.0/-0.0	PLATED	16
•	39.0	+3.0/-3.0	PLATED	16
○	40.0	+3.0/-3.0	PLATED	4
▫	40.0	+3.0/-3.0	PLATED	103
○	40.0	+3.0/-3.0	PLATED	39
○	40.0	+3.0/-3.0	PLATED	7
▵	40.0	+5.0/-0.0	PLATED	4
▵	45.0	+3.0/-3.0	PLATED	2
▯	59.0551	+3.0/-3.0	PLATED	2
C	62.0	+3.0/-3.0	PLATED	2
F	62.9921	+3.0/-3.0	PLATED	8
E	65.0	+3.0/-3.0	PLATED	10
•	65.0	+4.0/-0.0	PLATED	6
◦	35.5	+2.0/-0.0	NON-PLATED	2
H	66.0	+2.0/-0.0	NON-PLATED	2
I	125.0	+2.0/-2.0	NON-PLATED	4
K	125.0	+2.0/-2.0	NON-PLATED	2
J	128.0	+2.0/-2.0	NON-PLATED	2
▯	118.1102x31.4961	+3.0/-3.0	PLATED	1
⬭	118.1102x31.4961	+3.0/-3.0	PLATED	1
▯	137.7953x31.4961	+3.0/-3.0	PLATED	1

NOTES: UNLESS OTHERWISE SPECIFIED

1. MATERIAL: 370 HR
2. BOARD TO BE SOLDER MASK OVER BARE COPPER. TOP AND BOTTOM LAYERS FULL BODY ELECTROPLATED GOLD REQUIRED 250 uINCHES Ni AND 3-5 uINCHES Au.

   2.1. SELECTIVE HARD GOLD PLATING TO BE FLAT & PLATED 50-100uIN OF Au OVER 150-200uIN OF Ni. GOLD PLATING ON PAD SHOULD BE THE SAME LEVEL OR ABOVE THE SOLDER RESIST SURFACE ON TOP AND BOTTOM.

3. HOLES TO BE PLATED THROUGH. PLATING IN HOLES TO BE 0.001 MIN. THICK.
4. HOLE SIZES ARE AFTER PLATING.
5. SILKSCREEN BOTH SIDES, WHITE.
6. FABRICATE PER DIMENSIONS SHOWN.
7. SOLDER MASK TOP AND BOTTOM SIDES WITH LIQUID PHOTO IMAGABLE OR DRY FILM SOLDER MASK. COLOR GREEN.
8. TOTAL BOARD THICKNESS: 63 mil+/- 5% 08 LAYER CONSTRUCTION. REFER STACKUP
9. APPLY THIEVING AS REQUIRED.
10. WRAP OR TWIST SHOULD NOT EXCEED .005" PER INCH
11. BOARD MUST BE UL 94V-1 APPROVED, AND ROHS COMPLIANT.
12. FABRICATE BOARD PER IPC-A-600D STANDARD.
13. CLIP SILKSCREEN ON NO MASK AREA.
14. IMPEDANCE TOLERANCE SHOULD BE +/- 10%.
15. NO VENDOR LOGO, ART WORKS SHOULD NOT BE CHANGED WITHOUT PRIOR APPROVAL FROM PACTRON
16. DEBURR ALL SHARP EDGES
17. REMOVE UNUSED PADS IN ALL INNER LAYER
18. BOARD DIMENSIONS ARE IN INCHES
19. EDGE FINGER- CHAMFER EDGES MUST BE FREE OF CUTTING BURRS.

STACKUP: 8 LAYERS

CONTROLLED IMPEDANCE REQUIRED

		50 OHM SINGLE	100 OHM DIFFERENTIAL	90 OHM DIFFERENTIAL
	TOP SIDE SOLDER MASK (0.4-0.8 MIL)			
	COPPER THICKNESS-0.5oZ			
	PLATING THICKNESS-0.8 MIL			
	TOP (1.4 mil)	5.0 MILS	4.5/7.5 MILS	4.4 / 7.6 mils
FR-4	DIELECTRIC (3.2 mil)			
	GND1#2 (0.65 mil)			
FR-4	DIELECTRIC (4 mil)			
	SIG1#3 (1.3 mil)			
FR-4	DIELECTRIC (15 mil)	5.0 MILS	4.0/7.0 MILS	
	PWR1#4 (0.65 mil)			
FR-4	DIELECTRIC (8 mil)			
	PWR2#5 (0.65 mil)			
FR-4	DIELECTRIC (15 mil)			
	SIG2#6 (1.3 mil)	5.0 MILS	4.0/7.0 MILS	
FR-4	DIELECTRIC (4 mil)			
	GND2#7 (0.65 mil)			
FR-4	DIELECTRIC (3.2 mil)			
	BOTTOM (1.4 mil)	5.0 MILS	4.5/7.5 MILS	4.4 / 7.6 mils
	PLATING THICKNESS-0.8 MIL			
	COPPER THICKNESS-0.5oZ			
	BOTTOM SIDE SOLDER MASK (0.4-0.8 MIL)			

TOTAL THICKNESS: 63 mil+/- 5 %

NOTE: DIELECTRIC GLASS STYLE SHOULD NOT BE CHANGED WITHOUT PRIOR APPROVAL FROM PACTRON.

PACTRON
3000 PATRICK HENRY DRIVE, SANTA CLARA, CA 95054.
408-329-5500(PHONE), 408-747-1239(FAX).

PROJECT NAME	M2GL-M2S-EVAL-KIT Rev E	
PART NUMBER	DVP-102-000402-001	REV : E
DATE	OCT 2015	
PACTRON PART NUMBER	305-PD-15-0659	